

Technical data sheet

Product features



Chip dump scuttle heating from above infrared heat lamp

Model	SAP Code	00004881
UHL 11	A group of articles - web	Fryers and French Fries Holders



- Drain: No
- Maximum device temperature [°C]: 90
- Minimum device temperature [°C]: 30
- Heating location: Upper

SAP Code	00004881	Net Weight [kg]	5.50
Net Width [mm]	329	Power electric [kW]	0.500
Net Depth [mm]	555	Loading	230 V / 1N - 50 Hz
Net Height [mm]	342		

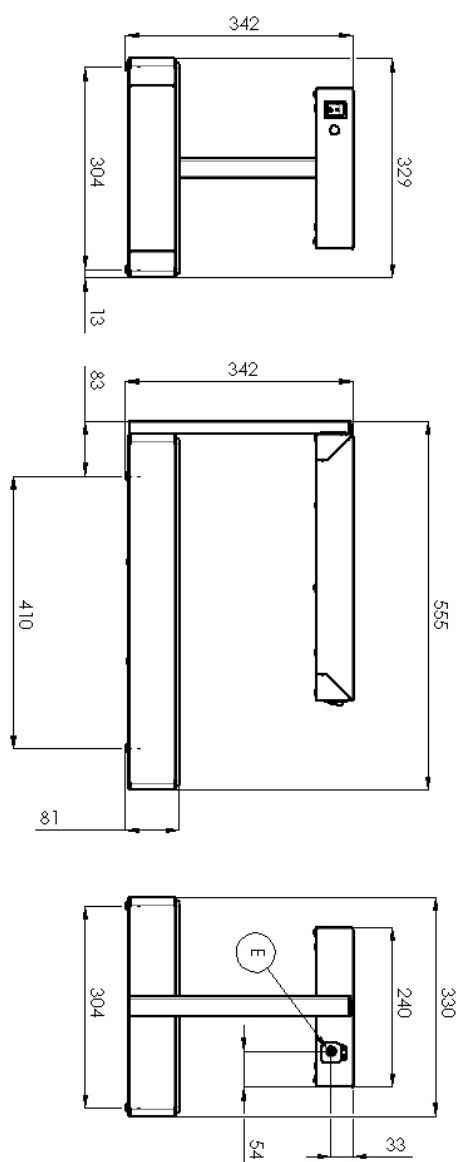
Technical data sheet

Technical drawing



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Product benefits

Chip dump scuttle heating from above infrared heat lamp

Model	SAP Code	00004881
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1

All-stainless steel bathtub

long life
resistance of AISI 304 stainless steel material
the material does not cut

2

Degree of protection of the control elements IPX4

maintenance-free system
resistance to splash water
long life

3

Upper heating

radiant heat from above as well

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Technical parameters



Chip dump scuttle heating from above infrared heat lamp

Model	SAP Code	00004881
UHL 11	A group of articles - web	Fryers and French Fries Holders

1. SAP Code:

00004881

2. Net Width [mm]:

329

3. Net Depth [mm]:

555

4. Net Height [mm]:

342

5. Net Weight [kg]:

5.50

6. Gross Width [mm]:

450

7. Gross depth [mm]:

575

8. Gross Height [mm]:

330

9. Gross Weight [kg]:

7.00

10. Device type:

Electric unit

11. Construction type of device:

Table top

12. Power electric [kW]:

0.500

13. Loading:

230 V / 1N - 50 Hz

14. Protection of controls:

IPX4

15. Indicators:

operation and warm-up

16. Device heating type:

Infrared emitter

17. Maximum device temperature [°C]:

90

18. Minimum device temperature [°C]:

30

19. Adjustable feet:

Yes

20. False bottom:

No

21. Drain:

No

22. Number of GN / EN:

1

23. GN / EN size in device:

GN 1/1

24. GN device depth:

65

25. Heating location:

Upper

26. Cross-section of conductors CU [mm²]:

0,5